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IN THE SPECIFICATION:

Please replace the full paragraph starting at line 14 and ending with line 26 on the first page 2 of the original specification with the following replacement paragraph showing the changes:

Microelectronic mechanical systems (MEMS) have progressed to forming channels and membranes for implementing fuel cells at the chip level. An example ~~if is~~ found in U.S. patent no. 6,312,846, by Marsh. This patent discloses fuel cell structures formed on the same wafer (the large substrate upon which many individual integrated circuit chips are formed). Typically the individual chips are cut out from the wafer and packaged individually. However, Marsh shows different functional circuits formed on different chips where the different chips remain on the same wafer. Interconnections then may be made by discrete wiring or deposition between the chips. These chips provide functions that include power conversion, conditioning and regulation. Power conversion, conditioning and regulation are used redundantly herein and in the art where the terms "conditioning," "conversion," and "regulation" may each include or exclude the other two depending on context.

Please replace the full paragraph starting at line 5 and ending with line 10 on the second page 2 of the original specification with the following replacement paragraph showing the changes:

In yet another preferred embodiment, ~~part parts~~ of the power converting, conditioning and controlling functions are constructed on a separate assembly or separate integrated circuit ~~with which also has~~ first electrical contact points. The integrated power system is then configured with electrical contact points corresponding the first electrical

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contact points, such that the at least one assembly can be mounted onto the chip and electrical connections made between the chip and the separate assembly or integrated circuit without using additional discrete electrical wires.

Please replace the full paragraph starting at line 5 and ending with line 14 on the second page 3 of the original specification with the following replacement paragraph showing the changes:

FIG. 2A shows, in cross section, the fuel cells 4, the controller functions 6 and 8 for the switching power supply and conditioning circuitry. The assembly of FIG. 2A shows the contact area for power integrated circuitry on the top side 20 of the chip, the "top" side is defined above. In this instance the connections between the fuel cell array 4 and circuit components integrated 22 are made by etched runs or grown layers within the chip. An integrated or even discrete circuit 24 may be mounted to the base chip 2. The item 24 ~~might contains~~ contain the conversion, regulation and control circuitry 6 and 8 (FIG. 1) while the power transistors 10 (FIG. 1) may be formed in the integrated area 22. In another embodiment, not shown, the conversion, regulating and control circuitry may also be formed within an integrated area on the chip.

Please replace the full paragraph starting at line 20 and ending with line 24 on the second page 3 of the original specification with the following replacement paragraph showing the changes:

The ~~actual~~ integration techniques that allow the above preferred embodiments include: monolithic integration of MOS and bipolar components, multiple chips mounted

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onto the same chip or carrier (chip on chip), and discrete mounted components in a more conventional hybrid approach. ~~Such~~ These individual assemblies and construction are well known in the art, but in each of these instances the above preferred embodiments of the present invention there is no discrete ~~or additional~~ wiring required to incorporate these assemblies and constructions inot the preferred embodiments. Prior art systems incorporating such assemblies and constructions make the electrical connections with discrete wires.